



## Final Product Change Notification

201301008F01

**Issue Date:** 23-Apr-2013

**Effective Date:** 23-Jul-2013

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### Change Category

- |   |   |   |  |
|---|---|---|--|
| <input checked="" type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input checked="" type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location             | <input type="checkbox"/> Assembly Location  | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

Release of 8 inch wafer diameter: products in SOT23, SOT323, SOT363, SOD323 package

### Details of this Change

Release of production using 8 inch wafer diameter for products in SOT23, SOT323, SOT363, SOD323 package.

Old products: Production using 6 inch wafer diameter.

Changed products: Production using 6 and 8 inch wafer diameter.

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

### Why do we Implement this Change

To increase flexibility and volume ramp-up.

### Identification of Affected Products

8 inch products can be identified by Lot No. after implementation

### Product Availability

### Sample Information

Samples are available upon request  
Latest sample request date for PCN samples is May 17, 2013.

### Production

Planned first shipment 01-Oct-2013

### Impact

Die size and active area remain unchanged. No change on external dimensions or mechanical behavior.  
Electrical parameters are unchanged (in specification and with the same distribution).

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Old products (using 6 inch wafer only) will be supplied until depleted.

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 23-May-2013.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** [DiscrQA.Helpdesk.GA-Products@nxp.com](mailto:DiscrQA.Helpdesk.GA-Products@nxp.com)

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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